

Listing of Claims:

Claims 1-20 (canceled)

21. (New) An electromagnetic radiation emitting or receiving surface mountable semiconductor device, comprising:

a housing including an opening with an open top, a closed bottom and sides connecting said closed bottom and said open top and a bottom wall at the closed bottom;

a conductor accommodated within said housing, said conductor having at least one first conductor portion and at least one second conductor portion being electrically isolated from each other;

at least one semiconductor chip positioned within said opening; and

a wire having a first wire end bonded to said at least one semiconductor chip and a second wire end bonded to said at least one second conductor portion such that said wire is positioned within said opening; wherein

said opening forms a window for sending or receiving electromagnetic radiation;

said first conductor portion has a first conductor end terminating in a first electrode external to said housing and a second conductor end extending along said opening and having a first open area exposed along said closed bottom such that said first conductor portion is substantially surrounded by said housing but for said first electrode and said first open area;

said second conductor portion has a third conductor end terminating in a second electrode external to said housing and a fourth conductor end extending along said opening and having a second open area exposed along said closed bottom such that said second conductor portion is substantially surrounded by said housing but for said second electrode and said second open area;

said bottom wall is positioned between said closed bottom and said second and fourth conductor ends such that said first and second open areas remain exposed;

said at least one semiconductor chip is bonded to said first open area; and

said second wire end is bonded to said second open area.

22. (New) The semiconductor device according to claim 21, wherein said first and second open areas are the only parts of said first and second conductor portions that are exposed within said opening.

23. (New) The semiconductor device according to claim 21, wherein said first and second conductor portions are coplanar.

24. (New) The semiconductor device according to claim 21, wherein said second and fourth conductor ends are in a first plane and said first and second open areas are in a second plane.

25. (New) The semiconductor device according to claim 21, wherein said second and fourth conductor ends are in a first plane and said first and second electrodes are in a second plane.

26. (New) The semiconductor device according to claim 21, wherein said housing is made of a reflective material wherein at least said closed bottom is reflective for said radiation.

27. (New) The semiconductor device according to claim 26, wherein said reflective material features a diffuse reflective degree of at least 80%.

28. (New) The semiconductor device according to claim 21, wherein said first and second electrodes wrap around a portion of said housing.

29. (New) The semiconductor device according to claim 28, wherein said first and second electrodes terminate on an external rear side of said housing which does not face the said window.

30. (New) The semiconductor device according to claim 21, wherein said second conductor end features a first offset comprising said first open area and said fourth conductor end features a second offset comprising the second open area.

31. (New) The semiconductor device according to claim 30, wherein said first and second offsets are offset toward said opening.

32. (New) The semiconductor device according to claim 24, wherein said second conductor end features a first offset comprising said first open area and said fourth conductor end features a second offset comprising the second open area.

33. (New) The semiconductor device according to claim 32, wherein said first and second offsets are offset toward said opening.

Respectfully submitted,

COHEN, PONTANI, LIEBERMAN & PAVANE

By: Thomas Langer
Thomas Langer
Reg. No. 27,264
551 Fifth Avenue, Suite 1210
New York, N.Y. 10176
(212) 687-2770

July 9, 2003